

1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任 何异议请及时告之,我们将妥善解决。

本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。

3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。

4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

# **Read Statement**

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets".

### Features

- Three High-side and Three Low-side Drivers
- Outputs Freely Configurable as Switch, Half Bridge or H-bridge
- Capable of Switching All Kinds of Loads Such as DC Motors, Bulbs, Resistors, Capacitors and Inductors
- 0.6 A Continuous Current Per Switch
- Low-side:  $R_{DSon} < 1.5 \Omega$  Versus Total Temperature Range
- High-side:  $R_{DSon} < 2.0 \Omega$  Versus Total Temperature Range
- Very Low Quiescent Current I<sub>S</sub> < 20  $\mu A$  in Standby Mode
- Outputs Short-circuit Protected
- Overtemperature Prewarning and Protection
- Undervoltage and Overvoltage Protection
- Various Diagnosis Functions Such as Shorted Output, Open Load, Overtemperature and Power Supply Fail
- Serial Data Interface
- Daisy Chaining Possible
- SSO20 Package

Dual Triple DMOS Output Driver with Serial Input Control

### Description

The T6817 is a fully protected driver interface designed in 0.8- $\mu$ m BCDMOS technology. It can be used to control up to 6 different loads by a microcontroller in automotive and industrial applications.

Each of the 3 high-side and 3 low-side drivers is capable of driving currents up to 600 mA. The drivers are freely configurable and can be controlled separately from a standard serial data interface. Therefore, all kinds of loads such as bulbs, resistors, capacitors and inductors can be combined. The IC design is especially supportive of H-bridges applications to drive DC motors.

Protection is guaranteed in terms of short-circuit conditions, overtemperature, underand overvoltage. Various diagnosis functions and a very low quiescent current in standby mode open a wide range of applications. Meeting automotive qualifications in the area of conducted interferences, EMC protection and 2 kV ESD protection provide added value and enhanced quality for the exacting requirements of automotive applications.

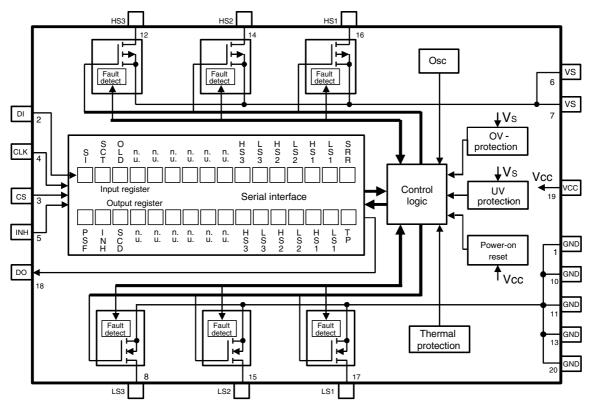
## **T6817**

Rev. 4670A-BCD-02/03



## AMEL

### Figure 1. Block Diagram



### **Pin Configuration**

Figure 2. Pinning SSO20

GND 🗆	1 ()	20	□ GND
DI 🗆	2	19	
CS 🗆	3	18	DO 🗆
CLK 🗆	4	17	⊒ LS1
INH 🗆	5	16	⊐ HS1
VS 🗆	6	15	□ LS2
VS 🗆	7	14	□ HS2
LS3 🗆	8	13	□ GND
n.c. 🗆	9	12	⊒ HS3
GND □	10	11	□ GND

### **Pin Description**

Pin	Symbol	Function
1	GND	Ground; reference potential; internal connection to Pin 10, 11, 13 and 20; cooling tab
2	DI	Serial data input; 5-V CMOS logic level input with internal pull-down; receives serial data from the control device, DI expects a 16-bit control word with LSB being transferred first
3	CS	Chip-select input; 5-V CMOS logic level input with internal pull-up; low = serial communication is enabled, high = disabled
4	CLK	Serial clock input; 5-V CMOS logic level input with internal pull down; controls serial data input interface and internal shift register (f <sub>max</sub> = 2 MHz)
5	INH	Inhibit input; 5-V logic input with internal pull-down; low = standby, high = normal operating
6, 7	VS	Power supply output stages HS1, HS2 and HS3
8	LS3	Low-side driver output 3; power-MOS open drain with internal reverse diode: overvoltage protection by active zenering; short-circuit protection; diagnosis for short and open load
9	n.c.	Not connected
10	GND	Ground (see Pin 1) be consistant
11	GND	Ground (see Pin 1)
12	HS3	High-side driver output 3; power-MOS open drain with internal reverse diode: overvoltage protection by active zenering; short-circuit protection; diagnosis for short and open load
13	GND	Ground (see Pin 1)
14	HS2	High-side driver output 2 (see Pin 12) be consistant
15	LS2	Low-side driver output 2 (see Pin 8)
16	HS1	High-side driver output 1 (see Pin 12)
17	LS1	Low-side driver output 1 (see Pin 8)
18	DO	Serial data output; 5-V CMOS logic level tri-state output for output (status) register data; sends 16-bit status information to the microcontroller (LSB is transferred first); output will remain tri-stated unless device is selected by CS = low, therefore, several ICs can operate on only one data output line only.
19	VCC	Logic supply voltage (5 V)
20	GND	Ground (see Pin 1)



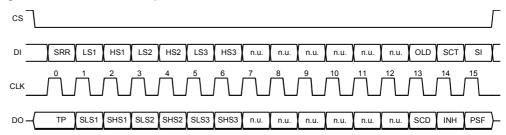


### **Functional Description**

### **Serial Interface**

Data transfer starts with the falling edge of the CS signal. Data must appear at DI synchronized to CLK and are accepted on the falling edge of the CLK signal. LSB (bit 0, SRR) has to be transferred first. Execution of new input data is enabled on the rising edge of the CS signal. When CS is high, Pin DO is in tri-state condition. This output is enabled on the falling edge of CS. Output data will change their state with the rising edge of CLK and stay stable until the next rising edge of CLK appears. LSB (bit 0, TP) is transferred first.

Figure 3. Data Transfer Input Data Protocol



#### Table 1. Input Data Protocol

Bit	Input Register	Function
0	SRR	Status register reset (high = reset; the bits PSF, SCD and overtemperature shutdown in the output data register are set to low)
1	LS1	Controls output LS1 (high = switch output LS1 on)
2	HS1	Controls output HS1 (high = switch output HS1 on)
3	LS2	See LS1
4	HS2	See HS1
5	LS3	See LS1
6	HS3	See HS1
7	n.u.	Not used
8	n.u.	Not used
9	n.u.	Not used
10	n.u.	Not used
11	n.u.	Not used
12	n.u.	Not used
13	OLD	Open load detection (low = on)
14	SCT	Programmable time delay for short circuit and overvoltage shutdown (short circuit shutdown delay high/low = 100 ms/12.5 ms, overvoltage shutdown delay high/low = 14 ms/3.5 ms
15	SI	Software inhibit; low = standby, high = normal operation (data transfer is not affected by standby function because the digital part is still powered)

4

Bit	Output (Status) Register	Function
0	TP	Temperature prewarning: high = warning (overtemperature shut- down, see remark below)
1	Status LS1	Normal operation: high = output is on, low = output is off Open-load detection: high = open load, low = no open load (correct load condition is detected if the corresponding output is switched off)
2	Status HS1	Normal operation: high = output is on, low = output is off Open-load detection: high = open load, low = no open load (correct load condition is detected if the corresponding output is switched off)
3	Status LS2	Description, see LS1
4	Status HS2	Description, see HS1
5	Status LS3	Description, see LS1
6	Status HS3	Description, see HS1
7	n.u.	Not used
8	n.u.	Not used
9	n.u.	Not used
10	n.u.	Not used
11	n.u.	Not used
12	n.u.	Not used
13	SCD	Short circuit detected: set high, when at least one output is switched off by a short circuit condition
14	INH	Inhibit: this bit is controlled by software (bit SI in input register) and hardware inhibit (Pin 17). High = standby, low = normal operation
15	PSF	Power supply fail: over- or undervoltage at Pin VS detected
Note:	Bit 0 to 15 = high: ov	ertemperature shutdown

Table 2. Output Data Protocol

Note: Bit 0 to 15 = high: overtemperature shutdown

#### After power-on reset, the input register has the following status:

Bit 15 (SI)	Bit 14 (SCT)	Bit 13 (OLD)	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6 (HS3)	Bit 5 (LS3)	Bit 4 (HS2)	Bit 3 (LS2)	Bit 2 (HS1)	Bit 1 (LS1)	Bit 0 (SRR)
Н	Н	н	n.u.	n.u.	n.u.	n.u.	n.u.	n.u.	L	L	L	L	L	L	L

### **Power-supply Fail**

In case of over- or undervoltage at Pin VS, an internal timer is started. When the undervoltage delay time ( $t_{dUV}$ ,  $t_{dOV}$ ) programmed by the SCT bit is reached, the power supply fail bit (PSF) in the output register is set and all outputs are disabled. When normal voltage is present again, the outputs are enabled immediately. The PSF bit remains high until it is reset by the SRR bit in the input register.





Open-load Detection	If the open-load detection bit (OLD) is set to low, a pull-up current for each high-side switch and a pull-down current for each low-side switch is turned on (open-load detection current $I_{HS1-3}$ , $I_{LS1-3}$ ). If $V_{VS}$ - $V_{HS1-3}$ or $V_{LS1-3}$ is lower than the open-load detection threshold (open-load condition), the corresponding bit of the output in the output register is set to high. Switching on an output stage with the OLD bit set to low disables the open-load function for this output. If bit SI is set to low, the open-load function is also switched off.
Overtemperature Protection	If the junction temperature exceeds the thermal prewarning threshold, $T_{jPW set}$ , the temperature prewarning bit (TP) in the output register is set. When the temperature falls below the thermal prewarning threshold, $T_{jPW reset}$ , the bit TP is reset. The TP bit can be read without transferring a complete 16-bit data word: with CS = high to low, the state of TP appears at Pin DO. After the microcontroller has read this information, CS is set high and the data transfer is interrupted without affecting the state of the input and output registers.
	If the junction temperature exceeds the thermal shutdown threshold, $T_{j \text{ switch off}}$ , the outputs are disabled and all bits in the output register are set high. The outputs can be enabled again when the temperature falls below the thermal shutdown threshold, $T_{j \text{ switch on}}$ , and when a high has been written to the SRR bit in the input register. Thermal prewarning and shutdown threshold have hysteresis.
Short-circuit Protection	The output currents are limited by a current regulator. Current limitation takes place when the overcurrent limitation and shutdown threshold $(I_{HS1-3}, I_{LS1-3})$ are reached. Simultaneously, an internal timer is started. The shorted output is disabled when during a permanent short the delay time $(t_{dSd})$ programmed by the short-circuit timer bit (SCT) is reached. Additionally, the short-circuit detection bit (SCD) is set. If the temperature prewarning bit TP in the output register is set during a short, the shorted output is disabled immediately and SCD bit is set. By writing a high to the SRR bit in the input register, the SCD bit is reset and the disabled outputs are enabled.
Inhibit	There are two ways to inhibit the T6817:
	<ol> <li>Set bit SI in the input register to zero</li> <li>Switch Pin 5 (INH) to 0 V</li> </ol>
	In both cases, all output stages are turned off but the serial interface stays active. The output stages can be activated again by bit $SI = 1$ and by Pin 5 (INH) switched back to

In both cases, all output stages are turned off but the serial interface stays active. The output stages can be activated again by bit SI = 1 and by Pin 5 (INH) switched back to 5 V.

T6817

6

### **Absolute Maximum Ratings**

All values refer to GND pins

Parameter	Pin	Symbol	Value	Unit
Supply voltage	6, 7	V <sub>VS</sub>	- 0.3 to +40	V
Supply voltage t < 0.5 s; $I_S$ > -2 A	6, 7	V <sub>VS</sub>	- 1	V
Supply voltage difference IV <sub>S_Pin6</sub> - V <sub>S_Pin7</sub> I		$\Delta V_{VS}$	150	mV
Supply current	6, 7	I <sub>VS</sub>	1.4	Α
Supply current t < 200 ms	6, 7	I <sub>VS</sub>	2.6	Α
Logic supply voltage	19	V <sub>VCC</sub>	-0.3 to 7	V
Input voltage	5	V <sub>INH</sub>	-0.3 to 17	V
Logic input voltage	2 to 4	V <sub>DI,</sub> V <sub>CLK,</sub> V <sub>CS</sub>	-0.3 to V <sub>VCC</sub> +0.3	V
Logic output voltage	18	V <sub>DO</sub>	-0.3 to V <sub>VCC</sub> +0.3	V
Input current	5, 2 to 4	I <sub>INH,</sub> I <sub>DI,</sub> I <sub>CLK,</sub> I <sub>CS</sub>	-10 to +10	mA
Output current	18	I <sub>DO</sub>	-10 to +10	mA
Output current	8, 12, 14 to 17	I <sub>LS1 to</sub> I <sub>LS3</sub> I <sub>HS1 to</sub> I <sub>HS3</sub>	Internal limited, see output specification	
Reverse conducting current ( $t_{Pulse} = 150 \ \mu s$ )	12, 14, 16 towards 6, 7	I <sub>HS1 to</sub> I <sub>HS3</sub>	17	А
Junction temperature range		T <sub>j</sub>	-40 to +150	°C
Storage temperature range		T <sub>STG</sub>	-55 to +150	°C

### **Thermal Resistance**

All values refer to GND pins

Parameter	Test Conditions	Symbol	Value	Unit
Junction - pin	Measured to GND Pins 1, 10, 11, 13 and 20	R <sub>thJP</sub>	25	K/W
Junction ambient		R <sub>thJA</sub>	65	K/W

## Operating Range All values refer to GND pins

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pins 6, 7	V <sub>VS</sub>	V <sub>UV</sub> <sup>(1)</sup>		40 (2)	V
Logic supply voltage	Pin 19	V <sub>VCC</sub>	4.5	5	5.5	V
Logic input voltage	Pin 2 to 4 and 5	$V_{\rm INH,} V_{\rm DI,} V_{\rm CLK,} V_{\rm CS}$	-0.3		V <sub>VCC</sub>	V
Serial interface clock frequency	Pin 4	f <sub>CLK</sub>			2	MHz
Junction temperature range		Tj	-40		150	°C

Notes: 1. Threshold for undervoltage detection 2. Outputs disabled for  $V_{VS} > V_{OV}$  (threshold for overvoltage detection)



## AIMEL

### Noise and Surge Immunity

Parameter	Test Conditions	Value
Conducted interferences	ISO 7637–1	Level 4 <sup>1)</sup>
Interference Suppression	VDE 0879 Part 2	Level 5
ESD (Human Body Model)	MIL-STM 5.1 – 1998	2 kV
ESD (Machine Model)	JEDEC EIA / JESD 22 – A115-A	150 V

Note: 1. Test pulse 5:  $V_{Smax} = 40 V$ 

### **Electrical Characteristics**

7.5 V < V<sub>VS</sub> < V<sub>OV</sub>; 4.5 V < V<sub>VCC</sub> < 5.5 V; INH = High; -40°C < T<sub>j</sub> < 150°C; unless otherwise specified, all values refer to GND pins.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
1	Current Consumption								
1.1	Quiescent current (VS)	V <sub>VS</sub> < 16 V, INH or bit SI = lo	6, 7	I <sub>VS</sub>			40	μA	А
1.2	Quiescent current (VCC)	4.5 V < V <sub>VCC</sub> < 5.5 V, INH or bit SI = low	19	I <sub>vcc</sub>			20	μA	А
1.3	Supply current (VS)	V <sub>VS</sub> < 16 V normal operating, all output stages off,	6, 7	I <sub>VS</sub>		0.8	1.2	mA	А
1.4	Supply current (VS)	V <sub>VS</sub> < 16 V normal operating, all output stages on, no load	6, 7	I <sub>VS</sub>			10	mA	A
1.5	Supply current (VCC)	4.5 V < V <sub>VCC</sub> < 5.5 V, normal operating Pin	19	I <sub>vcc</sub>			150	μA	А
2	Internal Oscillator Fre	equency							
2.1	Frequency (time base for delay timers)			f <sub>osc</sub>	19		45	kHz	A
3	Over- and Undervolta	ge Detection, Power-on	Reset						
3.1	Power-on reset threshold		19	V <sub>VCC</sub>	3.4	3.9	4.4	V	A
3.2	Power-on reset delay time	After switching on V <sub>VCC</sub>	19	t <sub>dPor</sub>	30	95	160	μS	A
3.3	Undervoltage detection threshold		6, 7	V <sub>UV</sub>	5.5		7.0	V	A
3.4	Undervoltage detection hysteresis		6, 7	$\Delta V_{UV}$		0.4		V	A
3.6	Undervoltage detection delay		6, 7	t <sub>dUV</sub>	7		21	ms	A
3.7	Overvoltage detection threshold		6, 7	V <sub>OV</sub>	18.0		22.5	v	A
38	Overvoltage detection hysteresis		6, 7	$\Delta V_{OV}$		1		v	A

\*) Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Note: 1. Delay time between rising edge of CS after data transmission and switch on/off output stages to 90% of final level

### **Electrical Characteristics (Continued)**

7.5 V < V<sub>VS</sub> < V<sub>OV</sub>; 4.5 V < V<sub>VCC</sub> < 5.5 V; INH = High; -40°C <  $T_j$  < 150°C; unless otherwise specified, all values refer to GND pins.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Туре
3.9	Undervoltage detection delay	Input register bit 14 (SCT) = high bit 14 (SCT) = low		t <sub>dOV</sub> t <sub>dOV</sub>	7 1.75		21 5.25	ms ms	A
4	Thermal Prewarning a	. ,		٩OV	1.75		0.20	113	
4.1	Thermal prewarning			T <sub>jPWset</sub>	125	145	165	°C	Α
4.2	Thermal prewarning			T <sub>jPWreset</sub>	105	125	145	°C	Α
4.3	Thermal prewarning hysteresis			$\Delta T_{jPW}$	3	20		к	А
4.4	Thermal shutdown			T <sub>j switch off</sub>	150	170	190	°C	Α
4.5	Thermal shutdown			T <sub>j switch on</sub>	130	150	170	°C	Α
4.6	Thermal shutdown hysteresis			$\Delta T_{j \text{ switch off}}$	3	20		к	А
4.7	Ratio thermal shutdown / thermal prewarning			T <sub>j switch off/</sub> T <sub>jPW set</sub>	1.05	1.17			A
4.8	Ratio thermal shutdown / thermal prewarning			T <sub>j switch on/</sub> T <sub>j</sub> PW reset	1.05	1.2			А
5	Output Specification	(LS1 - LS6, HS1 - HS6)	7.5 V < V	vs < V <sub>OV</sub>	1	1	1	1	1
5.1	On resistance	I <sub>Out</sub> = 600 mA	8, 15, 17	R <sub>DS OnL</sub>			1.5	Ω	A
5.2	On resistance	I <sub>Out</sub> = -600 mA	12, 14, 16	R <sub>DS OnH</sub>			2.0	Ω	Α
5.3	Output clamping voltage	I <sub>LS1-3</sub> = 50 mA	8, 15, 17	V <sub>LS1-3</sub>	40		60	V	A
5.4	Output leakage current	V <sub>LS1-3</sub> = 40 V all output stages off	8, 15, 17	I <sub>LS1–3</sub>			10	μA	A
5.5	Output leakage current	V <sub>HS1-3</sub> = 0 V all output stages off	2, 3, 12, 13, 15, 28	I <sub>HS1–3</sub>	-10			μA	A
5.7	Inductive shutdown energy		8, 12, 14 to 17	W <sub>outx</sub>			15	mJ	D
5.8	Output voltage edge steepness		8, 12, 14 to 17	dV <sub>LS1–3</sub> /dt dV <sub>HS1–3</sub> /dt	50	200	400	mV/µs	A
5.9	Overcurrent limitation and shutdown threshold		8, 15, 17	I <sub>LS1–3</sub>	650	950	1250	mA	A
5.10	Overcurrent limitation and shutdown threshold		12, 14, 16	I <sub>HS1–3</sub>	-1250	-950	-650	mA	A

\*) Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Note: 1. Delay time between rising edge of CS after data transmission and switch on/off output stages to 90% of final level





### **Electrical Characteristics (Continued)**

7.5 V < V<sub>VS</sub> < V<sub>OV</sub>; 4.5 V < V<sub>VCC</sub> < 5.5 V; INH = High; -40°C <  $T_j$  < 150°C; unless otherwise specified, all values refer to GND pins.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
5.11	Overcurrent	Input register							
	shutdown delay time	bit 14 (SCT) = high		t <sub>dSd</sub>	8	12	16	ms	A
		bit 14 (SCT) = low		t <sub>dSd</sub>	1.0	1.5	2.0	ms	А
5.12	Open load detection current	Input register bit 13 (OLD) =low, output off	8, 15, 17	I <sub>LS1-3</sub>	60		200	μA	A
5.13	Open load detection current	Input register bit 13 (OLD) =low, output off	12, 14, 16	I <sub>HS1–3</sub>	-150		-30	μA	A
5.14	Open load detection current ratio			I <sub>LS1–3 /</sub> I <sub>HS1–3</sub>	1.2				Α
5.15	Open load detection threshold	Input register bit 13 (OLD) =low, output off	8, 15, 17	V <sub>LS1-3</sub>	0.6		4	v	Α
5.16	Open load detection threshold	Input register bit 13 (OLD) =low, output off	12, 14, 16	V <sub>VS-</sub> V <sub>HS1-3</sub>	0.6		4	V	А
5.17	Output switch on delay <sup>1)</sup>	$R_{Load} = 1 \ k\Omega$		t <sub>don</sub>			0.5	ms	A
5.18	Output switch off delay <sup>1)</sup>	$R_{Load} = 1 \ k\Omega$		t <sub>doff</sub>			1	ms	A
6	Inhibit Input								
6.1	Input voltage low level threshold		5	V <sub>IL</sub>	$0.3 \times V_{VCC}$			V	A
6.2	Input voltage high level threshold		5	V <sub>IH</sub>			$0.7 \times V_{VCC}$	V	A
6.3	Hysteresis of input voltage		5	$\Delta V_{I}$	100		700	mV	A
6.4	Pull-down current	$V_{INH} = V_{VCC}$	5	I <sub>PD</sub>	10		80	μA	Α
7	Serial Interface – Logi	ic Inputs DI, CLK, CS	11			I			
7.1	Input voltage low- level threshold		2-4	V <sub>IL</sub>	$0.3 \times V_{VCC}$			v	А
7.2	Input voltage high- level threshold		2-4	V <sub>IH</sub>			$0.7 \times V_{VCC}$	v	Α
7.3	Hysteresis of input voltage		2-4	$\Delta V_{I}$	50		500	mV	Α
7.4	Pull-down current Pin DI, CLK	$V_{DI}, V_{CLK} = V_{VCC}$	2, 4	I <sub>PDSI</sub>	2		50	μA	Α
7.5	Pull-up current Pin CS	V <sub>CS</sub> = 0 V	3	I <sub>PUSI</sub>	-50		-2	μA	A

\*) Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Note: 1. Delay time between rising edge of CS after data transmission and switch on/off output stages to 90% of final level

### **Electrical Characteristics (Continued)**

7.5 V < V<sub>VS</sub> < V<sub>OV</sub>; 4.5 V < V<sub>VCC</sub> < 5.5 V; INH = High; -40°C <  $T_j$  < 150°C; unless otherwise specified, all values refer to GND pins.

	•								
No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
8	Serial Interface - Logic Output DO								
8.1	Output voltage low level	I <sub>OL</sub> = 3 mA	18	V <sub>DOL</sub>			0.5	V	А
8.2	Output voltage high level	I <sub>OL</sub> = -2 mA	18	V <sub>DOH</sub>	V <sub>VCC</sub> - 1 V			V	Α
8.3	Leakage current (tri-state)	$V_{CS} = V_{VCC,}$ 0 V < V_{DO} < V_{VCC}	18	I <sub>DO</sub>	-10		10	μA	А

\*) Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Note: 1. Delay time between rising edge of CS after data transmission and switch on/off output stages to 90% of final level

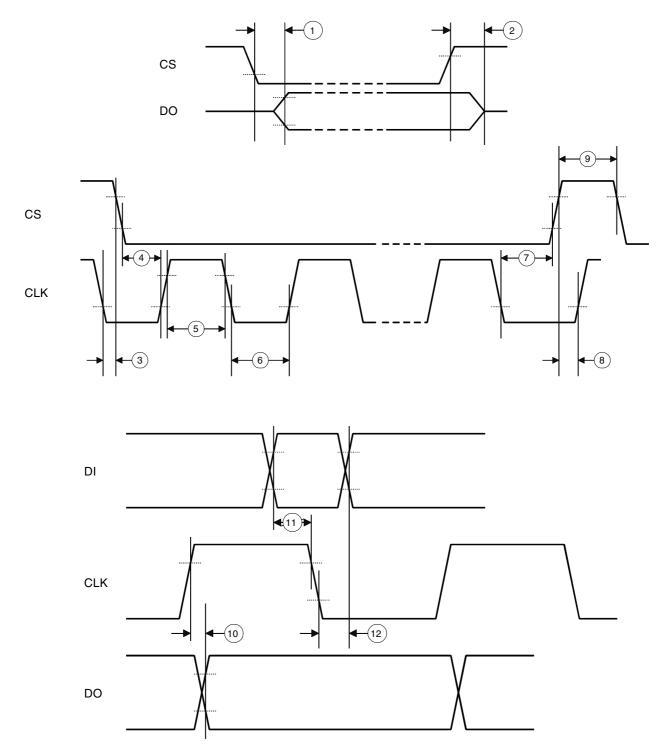
### Serial Interface – Timing

Parameters	Test Conditions	Timing Chart No.	Symbol	Min.	Тур.	Max.	Unit
DO enable after CS falling edge	C <sub>DO</sub> = 100 pF	1	t <sub>ENDO</sub>			200	ns
DO disable after CS rising edge	C <sub>DO</sub> = 100 pF	2	t <sub>DISDO</sub>			200	ns
DO fall time	C <sub>DO</sub> = 100 pF	-	t <sub>DOf</sub>			100	ns
DO rise time	C <sub>DO</sub> = 100 pF	-	t <sub>DOr</sub>			100	ns
DO valid time	C <sub>DO</sub> = 100 pF	10	t <sub>DOVal</sub>			200	ns
CS setup time		4	t <sub>CSSethl</sub>	225			ns
CS setup time		8	t <sub>CSSetlh</sub>	225			ns
CS high time	Input register Bit 14 (SCT) = high	9	t <sub>CSh</sub>	140			ms
CS high time	Input register Bit 14 (SCT) = Iow	9	t <sub>CSh</sub>	17.5			ms
CLK high time		5	t <sub>CLKh</sub>	225			ns
CLK low time		6	t <sub>CLKI</sub>	225			ns
CLK period time		-	t <sub>CLKp</sub>	500			ns
CLK setup time		7	t <sub>CLKSethl</sub>	225			ns
CLK setup time		3	t <sub>CLKSetlh</sub>	225			ns
DI setup time		11	t <sub>DIset</sub>	40			ns
DI hold time		12	t <sub>DIHold</sub>	40			ns



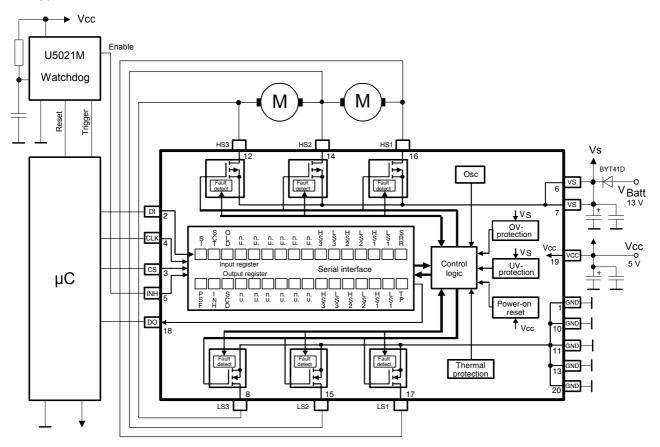


#### Figure 4. Serial Interface Timing with Chart Numbers



Inputs DI, CLK, CS: High level = 0.7 x V<sub>CC</sub>, low level = 0.3 x V<sub>CC</sub> Output DO: High level = 0.8 x V<sub>CC</sub>, low level = 0.2 x V<sub>CC</sub>

#### Figure 5. Application Circuit



### **Application Notes**

It is strongly recommended that the blocking capacitors at  $V_{CC}$  and  $V_S$  be connected as close as possible to the power supply and GND pins.

Recommended value for capacitors at V<sub>S</sub>:

Electrolythic capacitor C > 22  $\mu$ F in parallel with a ceramic capacitor C = 100 nF. Value for electrolytic capacitor depends on external loads, conducted interferences and reverse conducting current I<sub>HSX</sub> (see: Absolut Maximum Ratings).

Recommended value for capacitors at  $V_{CC}$ : Electrolythic capacitor C > 10  $\mu$ F in parallel with a ceramic capacitor C = 100 nF.

To reduce thermal resistance it is recommended that cooling areas be placed on the PCB as close as possible to GND pins.

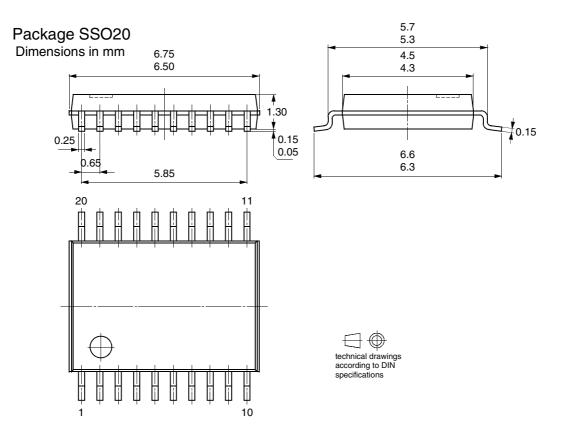




### **Ordering Information**

Extended Type Number	Package	Remarks
T6817-TKS	SSO20	Power package, tube
T6817-TKQ	SSO20	Power package, taped and reeled

### **Package Information**





#### **Atmel Headquarters**

Corporate Headquarters 2325 Orchard Parkway San Jose, CA 95131 TEL 1(408) 441-0311 FAX 1(408) 487-2600

#### Europe

Atmel Sarl Route des Arsenaux 41 Case Postale 80 CH-1705 Fribourg Switzerland TEL (41) 26-426-5555 FAX (41) 26-426-5500

#### Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimhatsui East Kowloon Hong Kong TEL (852) 2721-9778 FAX (852) 2722-1369

#### Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan TEL (81) 3-3523-3551 FAX (81) 3-3523-7581

#### **Atmel Operations**

Memory 2325 Orchard Parkway San Jose, CA 95131 TEL 1(408) 441-0311 FAX 1(408) 436-4314

*Microcontrollers* 2325 Orchard Parkway San Jose, CA 95131 TEL 1(408) 441-0311 FAX 1(408) 436-4314

La Chantrerie BP 70602 44306 Nantes Cedex 3, France TEL (33) 2-40-18-18-18 FAX (33) 2-40-18-19-60

#### ASIC/ASSP/Smart Cards

Zone Industrielle 13106 Rousset Cedex, France TEL (33) 4-42-53-60-00 FAX (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 TEL 1(719) 576-3300 FAX 1(719) 540-1759

Scottish Enterprise Technology Park Maxwell Building East Kilbride G75 0QR, Scotland TEL (44) 1355-803-000 FAX (44) 1355-242-743

#### **RF**/Automotive

Theresienstrasse 2 Postfach 3535 74025 Heilbronn, Germany TEL (49) 71-31-67-0 FAX (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 TEL 1(719) 576-3300 FAX 1(719) 540-1759

#### *Biometrics/Imaging/Hi-Rel MPU/*

High Speed Converters/RF Datacom Avenue de Rochepleine BP 123 38521 Saint-Egreve Cedex, France TEL (33) 4-76-58-30-00 FAX (33) 4-76-58-34-80

*e-mail* literature@atmel.com

Web Site http://www.atmel.com

#### © Atmel Corporation 2003.

Atmel Corporation makes no warranty for the use of its products, other than those expressly contained in the Company's standard warranty which is detailed in Atmel's Terms and Conditions located on the Company's web site. The Company assumes no responsibility for any errors which may appear in this document, reserves the right to change devices or specifications detailed herein at any time without notice, and does not make any commitment to update the information contained herein. No licenses to patents or other intellectual property of Atmel are granted by the Company in connection with the sale of Atmel products, expressly or by implication. Atmel's products are not authorized for use as critical components in life support devices or systems.

Atmel<sup>®</sup> is the registered trademark of Atmel.

Other terms and product names may be the trademarks of others.

